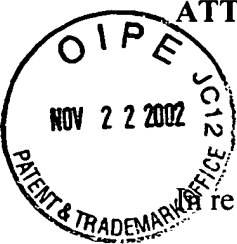


2823

ATTORNEY DOCKET NO.: CHITTIPEDDI 59-108

PATENT RECEIVED
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#23/D



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of: Sailish Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

12/24/02
VJ

Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 11/14/2002 (Date)
EDITH SHEIK
(Printed or typed name of person signing the certificate)
Edith Sheik
(Signature of the person signing the certificate)

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Office Action mailed August 26, 2002, please amend the above-identified Application as follows:

IN THE CLAIMS:

Please amend Claim 1 as follows:

Sub E
D

~~1. (Three Times Amended) A wire bonding method, comprising the steps of:
forming a semiconductor substrate with a copper (Cu) interconnect material;~~